



Final Product Change Notification

201411005F01

Issue Date: 26-Jan-2015

Effective Date: 10-May-2015

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For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT363

Details of this Change

Scheduled changes affect product types in SOT363 package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of change to copper wire as given by implementation date below. Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound supplier will be introduced for copper wire products.

Old product: wire material is Au (with currently used mold compound suppliers)

Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 25-Feb-2015.

Production

Planned first shipment 10-May-2015

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 25-Feb-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Customer Part#	Changed Part Description	Package Outline
BAW56S,115	BAW56S,115	Switching diode	SOT363
BC856BS,115	BC856BS,115	General-purpose transistor	SOT363
PUMH11,115	PUMH11,115	RET	SOT363
PUMD2,115	PUMD2,115	RET	SOT363
PUMH1,115	PUMH1,115	RET	SOT363
PUMH4,115	PUMH4,115	RET	SOT363
PUMH7,115	PUMH7,115	RET	SOT363
PUMD9,115	PUMD9,115	RET	SOT363
PUMD9,115	PUMD9,115	RET	SOT363
PUMD10,115	PUMD10,115	RET	SOT363
BC846S,115	BC846S,115	General-purpose transistor	SOT363
BC846S,115	BC846S,115	General-purpose transistor	SOT363
BC846S,125	BC846S,125	General-purpose transistor	SOT363
BC846S,125	BC846S,125	General-purpose transistor	SOT363
PUMD12,115	PUMD12,115	RET	SOT363
PUMB2,115	PUMB2,115	RET	SOT363
PUMD48,115	PUMD48,115	RET	SOT363
PUMH9,115	PUMH9,115	RET	SOT363
BC856S,115	BC856S,115	General-purpose transistor	SOT363
PUMH2,115	PUMH2,115	RET	SOT363
PUMH2,115	PUMH2,115	RET	SOT363
PUMH10,115	PUMH10,115	RET	SOT363
PUMD13,115	PUMD13,115	RET	SOT363
PUMB11,115	PUMB11,115	RET	SOT363
PUMB11,115	PUMB11,115	RET	SOT363
BAT754L,115	BAT754L,115	Schottky diode	SOT363
BAV99S,115	BAV99S,115	Switching diode	SOT363
BAV99S,135	BAV99S,135	Switching diode	SOT363
PBSS2515YPN,115	PBSS2515YPN,115	BISS	SOT363
PBSS2515YPN,115	PBSS2515YPN,115	BISS	SOT363
PUMB3,115	PUMB3,115	RET	SOT363
BAS16VY,115	BAS16VY,115	Switching diode	SOT363
BAW101S,115	BAW101S,115	Switching diode	SOT363
PUMB13,115	PUMB13,115	RET	SOT363
PUMB13,115	PUMB13,115	RET	SOT363
PUMD15,115	PUMD15,115	RET	SOT363
PUMD16,115	PUMD16,115	RET	SOT363
PUMH13,115	PUMH13,115	RET	SOT363
PUMH17,115	PUMH17,115	RET	SOT363
PUMH18,115	PUMH18,115	RET	SOT363
PUMH20,115	PUMH20,115	RET	SOT363
PUMH20,115	PUMH20,115	RET	SOT363
BCM847BS,115	BCM847BS,115	Matched pair	SOT363
BCM847BS,135	BCM847BS,135	Matched pair	SOT363

PBLS4003Y,115	PBLS4003Y,115	Loadswitch	SOT363
PBLS4005Y,115	PBLS4005Y,115	Loadswitch	SOT363
BCM857BS,115	BCM857BS,115	Matched pair	SOT363
BCM857BS,135	BCM857BS,135	Matched pair	SOT363
PMP4201Y,115	PMP4201Y,115	Matched pair	SOT363
PMP4201Y,135	PMP4201Y,135	Matched pair	SOT363
PMP4201Y,135	PMP4201Y,135	Matched pair	SOT363
PMP5201Y,115	PMP5201Y,115	Matched pair	SOT363
BAT54XY,115	BAT54XY,115	SCHOTTKY DIODE	SOT363
BAT54XY,115	BAT54XY,115	SCHOTTKY DIODE	SOT363
PMBT3946YPN,115	PMBT3946YPN,115	GENERAL PURPOSE TRANSISTOR	SOT363
BCM856BS,115	BCM856BS,115	COMPLEX DISCRETE	SOT363
BCM856BSH	BCM856BSH	COMPLEX DISCRETE	SOT363
BC846BPN,115	BC846BPN,115	General-purpose transistor	SOT363
BC846BPN,115	BC846BPN,115	General-purpose transistor	SOT363
BC846BS,115	BC846BS,115	General-purpose transistor	SOT363
BAW56S,115	BAW56S,115	Switching diode	SOT363